

# M2802-VB Datasheet Dual N-Channel 20 V (D-S) MOSFET

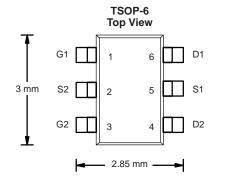
PRODUCT SUMMARY						
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)			
20	0.022 at $V_{GS}$ = 4.5 V	6.0	1.8 nC			
	0.028 at V <sub>GS</sub> = 2.5 V	5.0	1.0 HC			

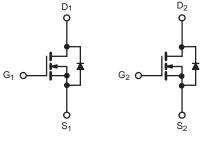
#### FEATURES

- Halogen-free According to IEC 61249-2-21
   Definition
- Trench Power MOSFET
- 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC



COMPLIANT





N-Channel MOSFET

N-Channel MOSFET

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	20	V	
Gate-Source Voltage		V <sub>GS</sub>	± 12		
	T <sub>C</sub> = 25 °C		6.0		
Continuous Drain Current ( $T_1 = 150 \ ^{\circ}C$ )	T <sub>C</sub> = 70 °C	I <sub>D</sub>	4.0		
	T <sub>A</sub> = 25 °C	טי	3.5 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C	1	2.8 <sup>b, c</sup>	A	
Pulsed Drain Current		I <sub>DM</sub>	18		
	T <sub>C</sub> = 25 °C		1.17		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	۱ <sub>s</sub>	0.95 <sup>b, c</sup>		
	T <sub>C</sub> = 25 °C		1.6		
Maximum Power Dissipation	T <sub>C</sub> = 70 °C	PD	1.0	w	
	T <sub>A</sub> = 25 °C	'D	1.14 <sup>b, c</sup>	vv	
	T <sub>A</sub> = 70 °C	1	0.73 <sup>b, c</sup>		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	**	
Soldering Recommendations (Peak Temperature) <sup>d, e</sup>			260		

#### THERMAL RESISTANCE RATINGS

Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 5 s	R <sub>thJA</sub>	93	110	°C/W
Maximum Junction-to-Foot	Steady State	R <sub>thJF</sub>	75	90	0/00

Notes:

a.  $T_C = 25 \ ^{\circ}C.$ 

b. Surface Mounted on 1" x 1" FR4 board.

c. t = 5 s.

d. Maximum under steady state conditions is 150  $^{\circ}\text{C/W}.$ 



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static	<u> </u>				•	1
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 V, I_{D} = 250 \mu A$	20			V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	L 050 ··· A		29		mV/°C
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA		- 4		
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \ \mu A$	0.4		1.5	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA
	I <sub>DSS</sub>	$V_{DS} = 20 V, V_{GS} = 0 V$			1	μA
Zero Gate Voltage Drain Current		$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			10	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	10			Α
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 3.4 A		0.022		Ω
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 2.5 V, I <sub>D</sub> = 3.0 A		0.028		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 3.4 A		10		S
Dynamic <sup>b</sup>					1	1
Input Capacitance	C <sub>iss</sub>			400		
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz		55		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			26		
Total Gate Charge	Q <sub>g</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 3.4 \text{ A}$		3.7	6	nC
				1.8	3	
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ = 10 V, $V_{GS}$ = 4.5 V, $I_{D}$ = 3.4 A		0.74		
Gate-Drain Charge	Q <sub>gd</sub>			0.42		
Gate Resistance	Rg	f = 1 MHz	1	5	10	Ω
Turn-On Delay Time	t <sub>d(on)</sub>			10	20	- ns
Rise Time	t <sub>r</sub>	$V_{DD} = 10 \text{ V}, \text{ R}_{L} = 5.6 \Omega$		15	30	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 2.7 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		10	20	
Fall Time	t <sub>f</sub>			10	20	
Turn-On Delay Time	t <sub>d(on)</sub>			5	10	
Rise Time	t <sub>r</sub>	$V_{DD} = 10 \text{ V}, \text{R}_{\text{L}} = 5.6 \Omega$		15	30	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 2.7 \text{ A}, V_{GEN} = 10 \text{ V}, \text{ R}_g = 1 \Omega$		10	20	
Fall Time	t <sub>f</sub>	-		10	20	
Drain-Source Body Diode Characteristic	cs				•	1
Continuous Source-Drain Diode Current	ا <sub>S</sub>	T <sub>C</sub> = 25 °C		1.2		•
Pulse Diode Forward Current	I <sub>SM</sub>			18		A
Body Diode Voltage	V <sub>SD</sub>	$I_{S} = 2.7 \text{ A}, V_{GS} = 0 \text{ V}$		0.85	1.2	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>			10	20	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			4	10	nC
Reverse Recovery Fall Time	ta	$I_F = 2.7 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		6		
Reverse Recovery Rise Time	t <sub>b</sub>			4		ns

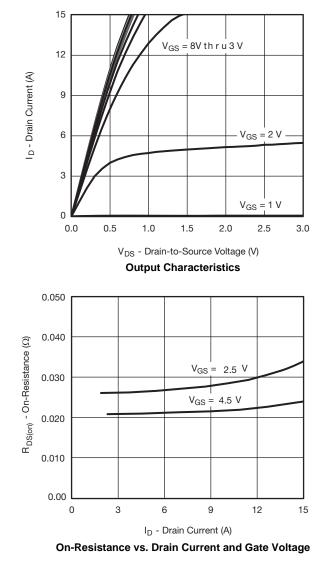
Notes:

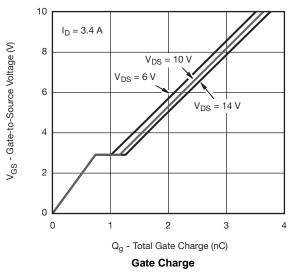
a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %

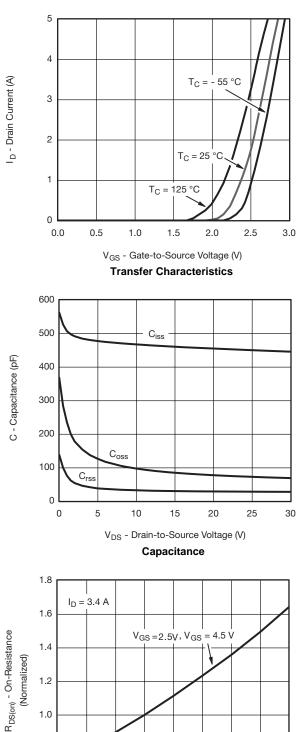
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.









1.0

0.8

0.6

- 50

- 25

0

25

50

T<sub>J</sub> - Junction Temperature (°C)

**On-Resistance vs. Junction Temperature** 

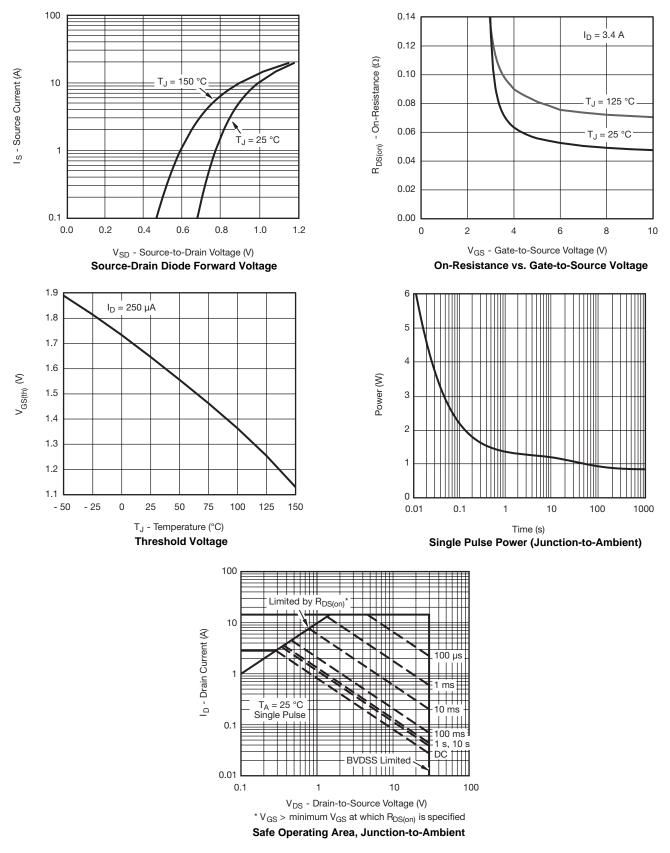
75

100

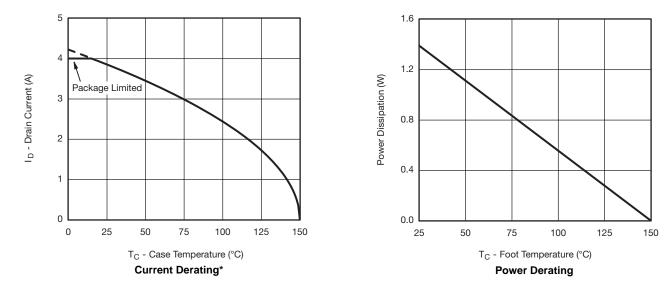
125

150



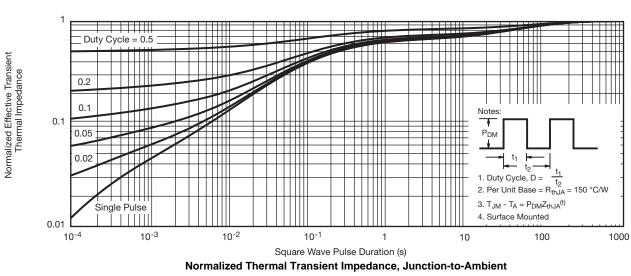


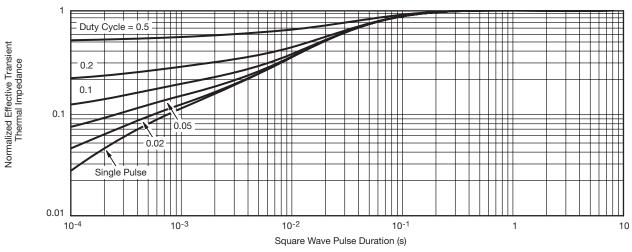




\* The power dissipation  $P_D$  is based on  $T_{J(max)}$  = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



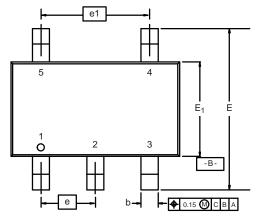




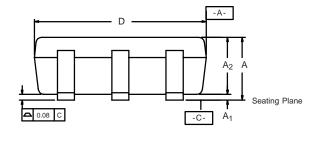
Normalized Thermal Transient Impedance, Junction-to-Foot

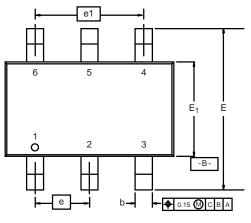


TSOP: 5/6-LEAD JEDEC Part Number: MO-193C

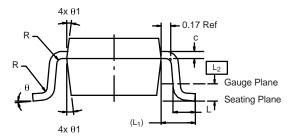








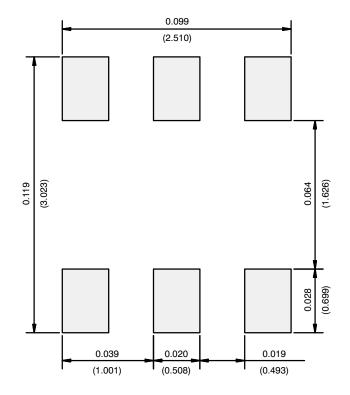
6-LEAD TSOP



	MIL	LIMETER	RS	INCHES			
Dim	Min	Nom	Max	Min	Nom	Max	
Α	0.91	-	1.10	0.036	-	0.043	
A <sub>1</sub>	0.01	-	0.10	0.0004	-	0.004	
A <sub>2</sub>	0.90	-	1.00	0.035	0.038	0.039	
b	0.30	0.32	0.45	0.012	0.013	0.018	
С	0.10	0.15	0.20	0.004	0.006	0.008	
D	2.95	3.05	3.10	0.116	0.120	0.122	
Е	2.70	2.85	2.98	0.106	0.112	0.117	
E <sub>1</sub>	1.55	1.65	1.70	0.061	0.065	0.067	
е	0.95 BSC			0.0374 BSC			
<b>e</b> 1	1.80	1.90	2.00	0.071	0.075	0.079	
L	0.32	-	0.50	0.012	-	0.020	
L <sub>1</sub>		0.60 Ref		0.024 Ref			
L <sub>2</sub>	0.25 BSC			0.010 BSC			
R	0.10	-	-	0.004	-	-	
θ	0°	4°	8°	0°	4°	8°	
$\theta_1$	7° Nom			7° Nom			
ECN: C-06593-Rev. I, 18-Dec-06 DWG: 5540							



#### **RECOMMENDED MINIMUM PADS FOR TSOP-6**



Recommended Minimum Pads Dimensions in Inches/(mm)



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